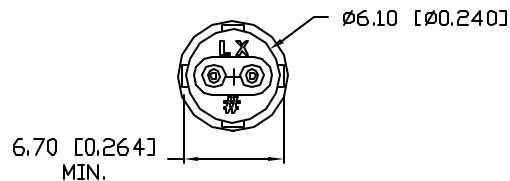
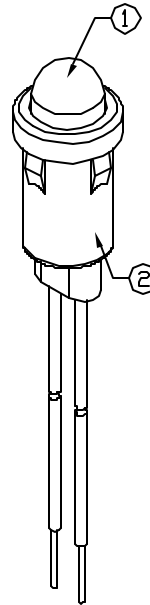
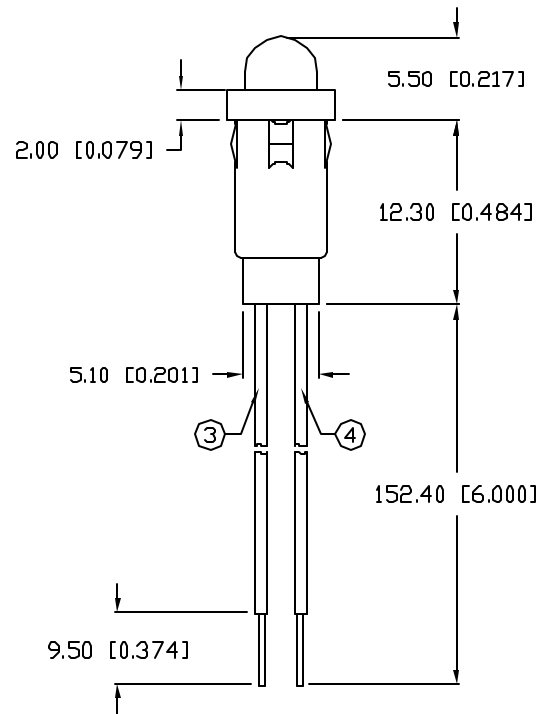
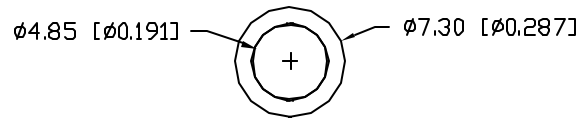


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PART NUMBER
SSI-LXH600SYD-150

REV.



PANEL HOLE: $\varnothing 0.250^*$
PANEL THICKNESS: 0.030" MIN.

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^{\circ}\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		590		nm	
FORWARD VOLTAGE		2.0	2.5	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		100		med	$I_f=20\text{mA}$
VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	YELLOW				
EPOXY LENS FINISH:	YELLOW DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C
SOLDERING TEMP.	+260	°C
2.0mm FROM BODY		3 SEC. MAX

* $t < 10\mu\text{s}$

NOTES:

1. SSL-LX509F3SYD LED.
2. SSH-LXH600 HOLDER, BLACK.
3. ANODE LEAD: LXP-WST24RDT0C, 24 AWG STRANDED, TOP OVERCOAT, RED INSULATION, CUT 160mm LONG, STRIP 4mm & 9.5mm.
4. CATHODE LEAD: LXP-WST24BLT0C, 24 AWG STRANDED, TOP OVERCOAT, BLACK INSULATION, CUT 160mm LONG, STRIP 4mm & 9.5mm.

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*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN= ^{+DECIMAL PRECISION} _{-0.00} MAX= ^{+0.00} _{-DECIMAL PRECISION}

REV.

PART NUMBER

SSI-LXH600SYD-150

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T-5mm (T-1 3/4) LED, PANEL MOUNT INDICATOR,
590nm SUPER YELLOW LED, YELLOW DIFFUSED LENS.
WITH 6" WIRE LEADS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:

GT

CHECKED BY:

APPROVED BY:

DATE: 7.25.01

PAGE: 1 OF 1

SCALE: N/A